

SOT1688-1(SC)

HLQFN16; plastic, thermal enhanced low profile quad flat non-leaded package; 16 terminals; 0.8 mm pitch; 4 mm x 4 mm x 1.45 mm body

9 December 2020

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HLQFN16
Package type industry code	HLQFN16
Package style descriptive code	HLQFN (thermal enhanced low profile quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	11-09-2019
Manufacturer package code	98ASA00761D

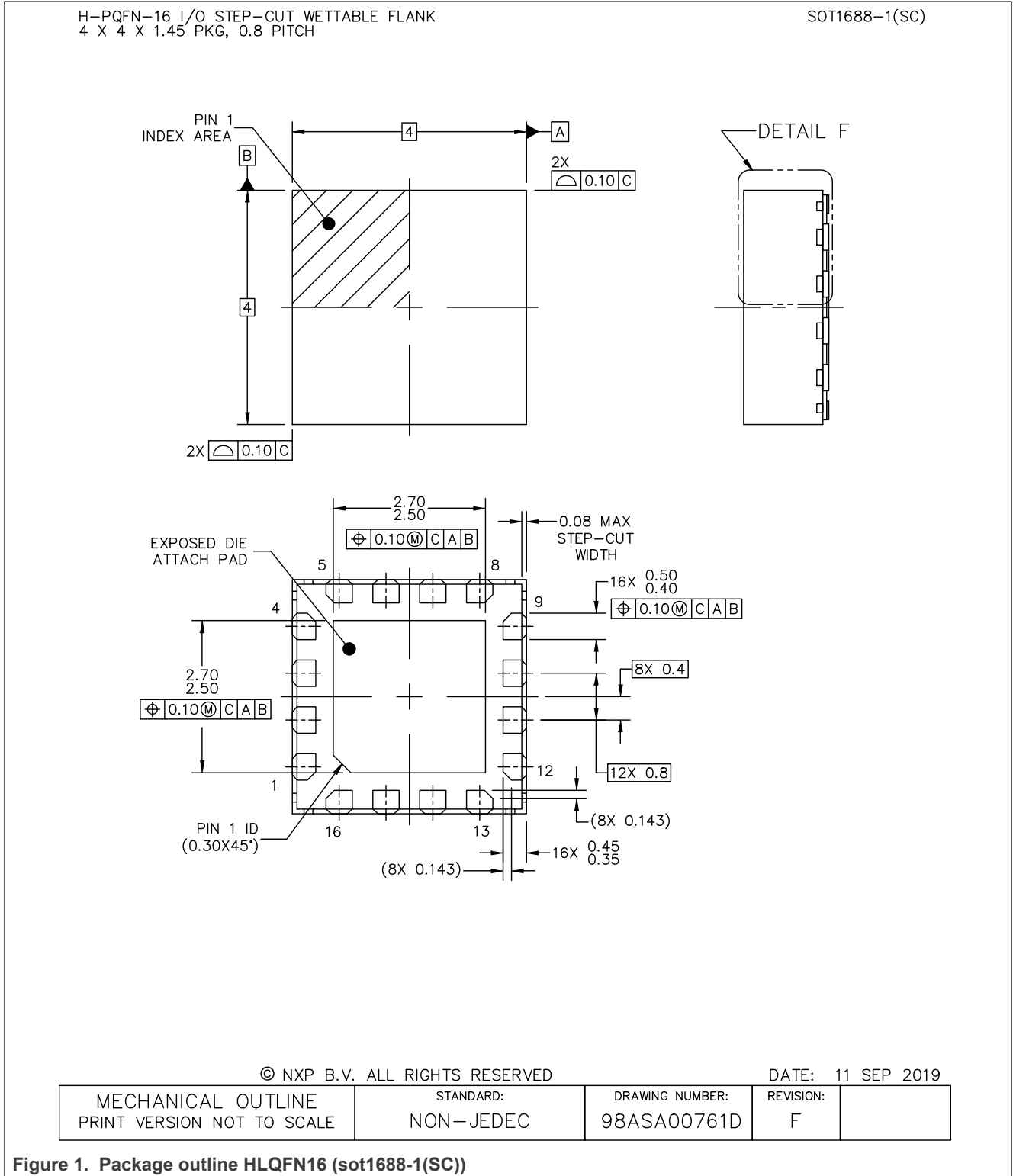
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	3.9	4	4.1	mm
package width	3.9	4	4.1	mm
seated height	1.4	1.45	1.5	mm
nominal pitch	-	0.8	-	mm
actual quantity of termination	-	16	-	

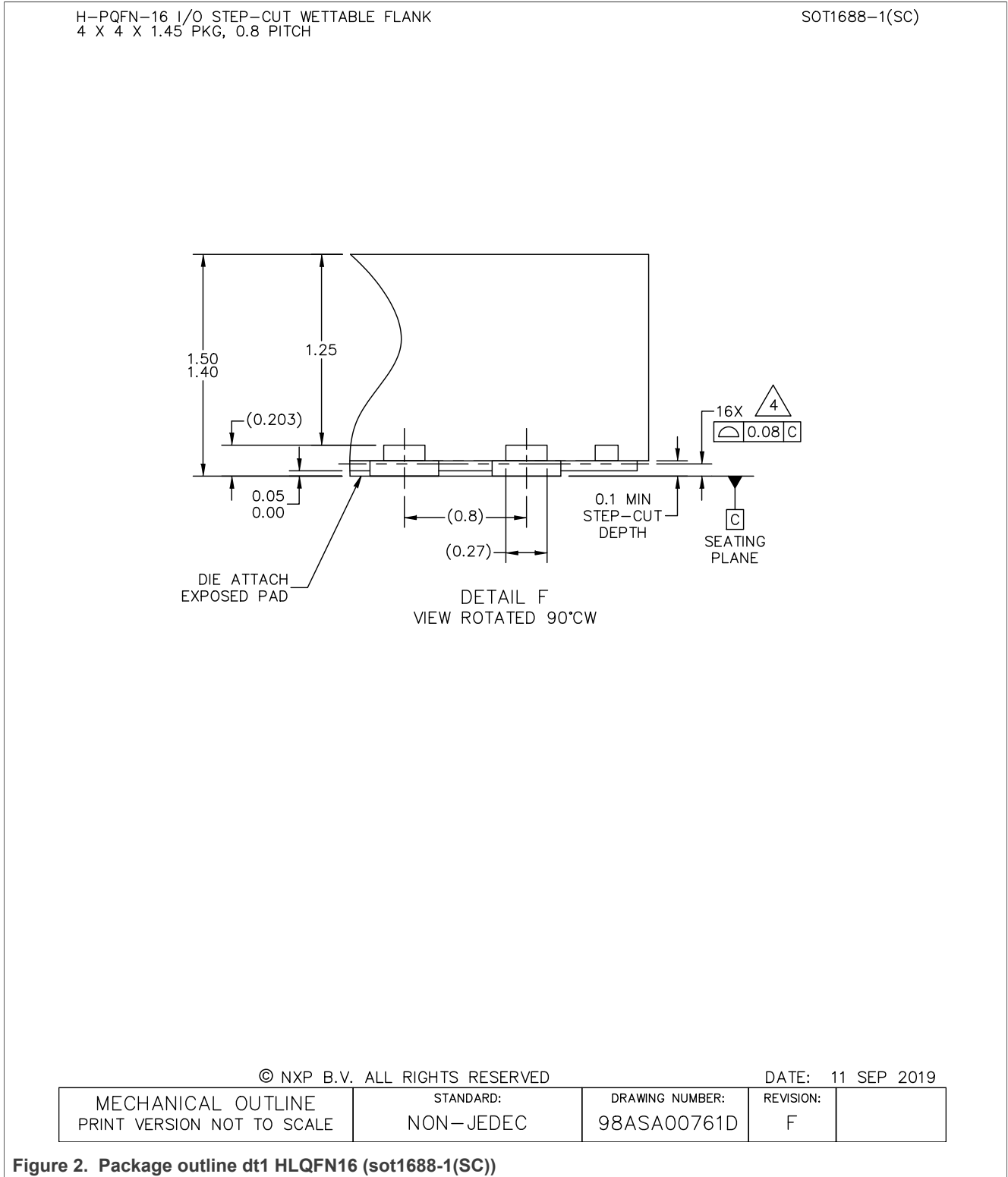


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2 Package outline



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3 Soldering

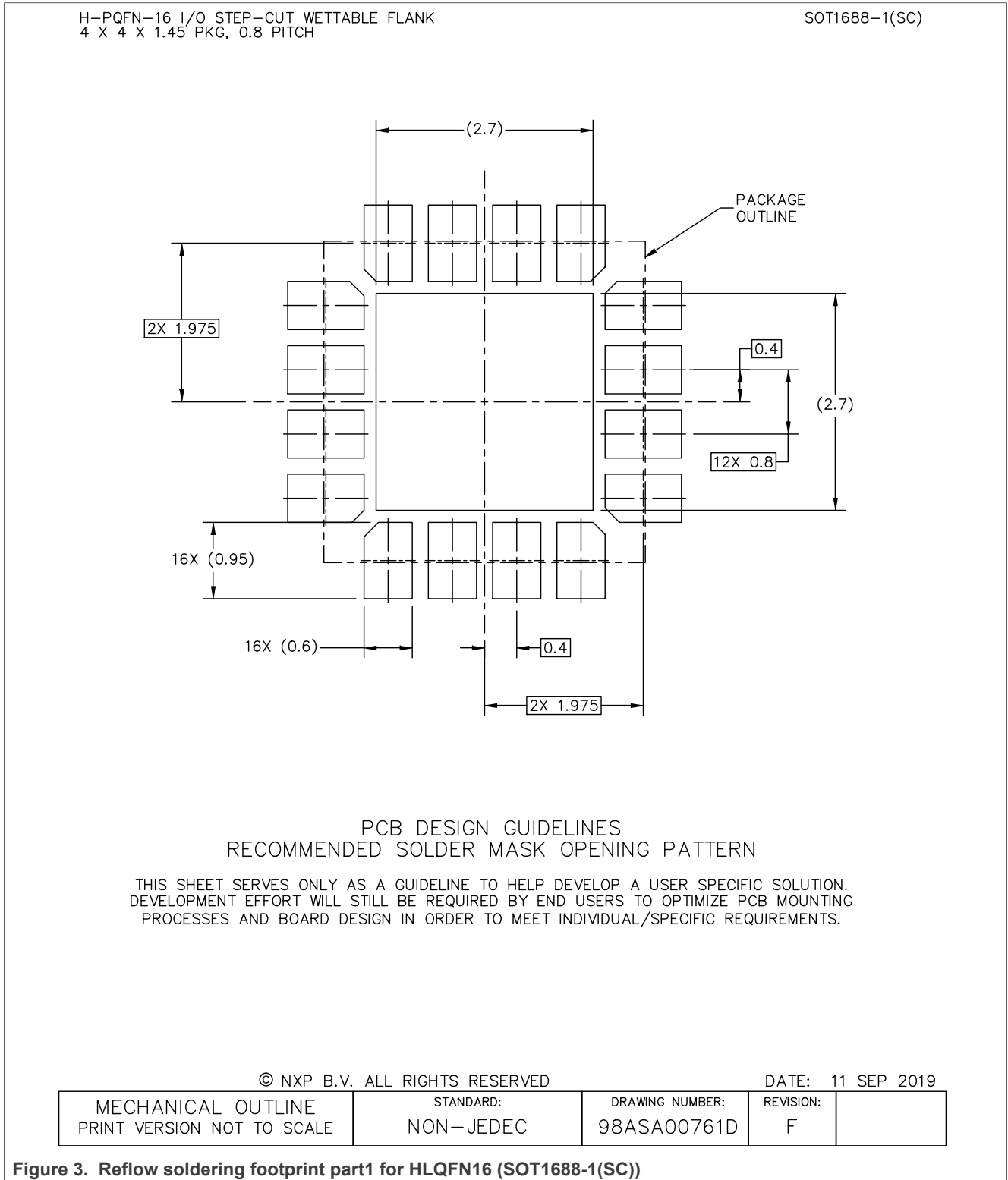
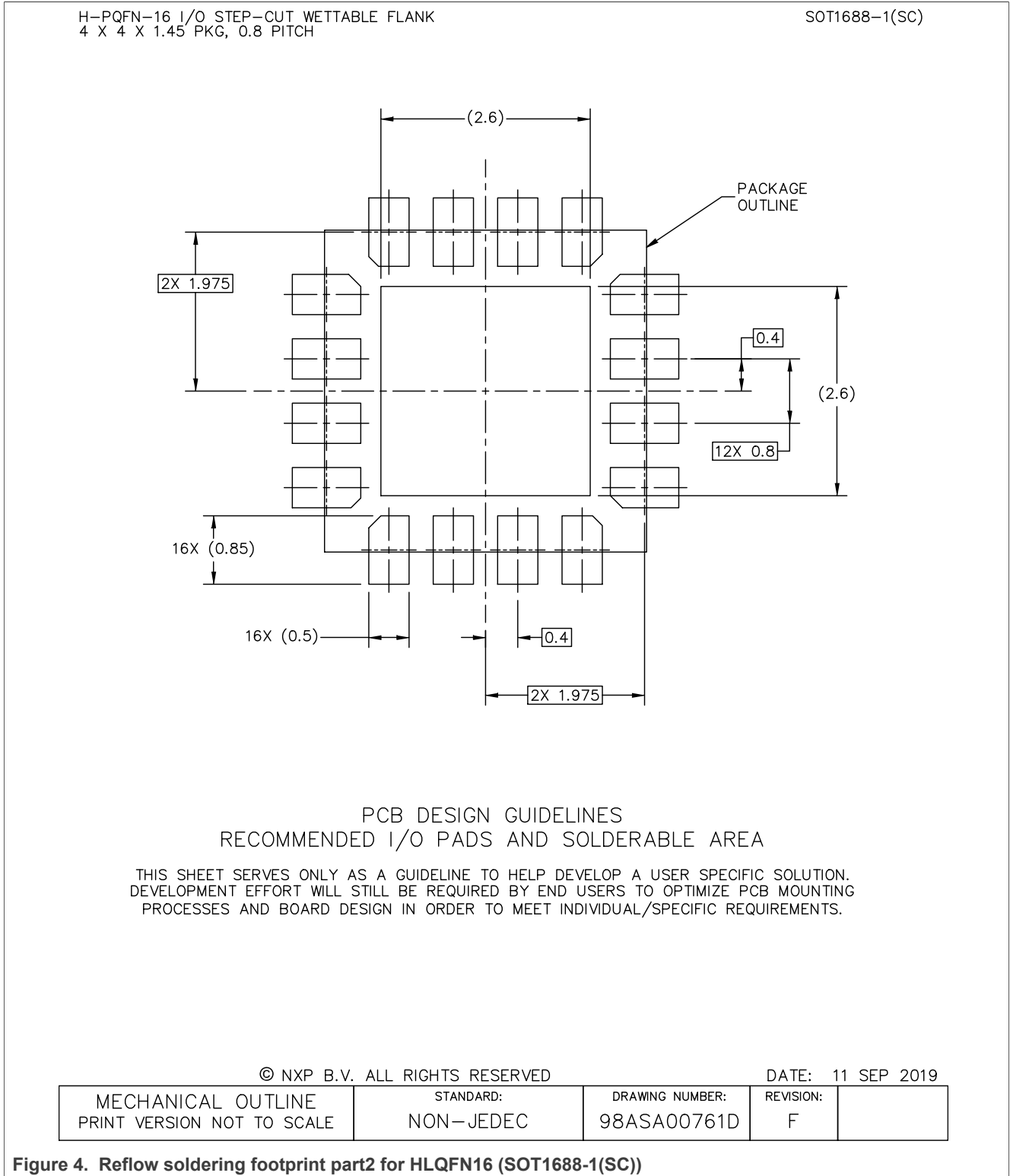
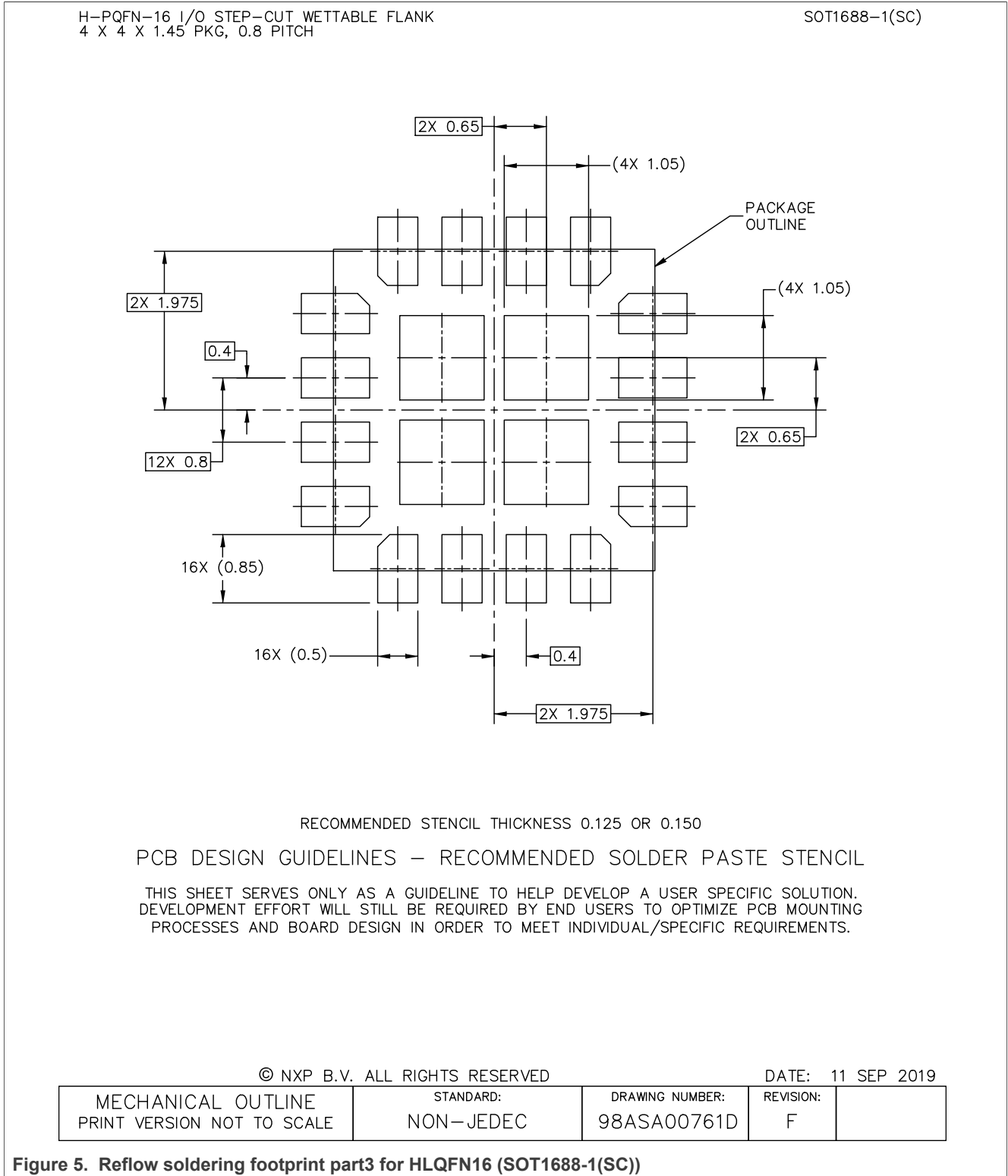


Figure 3. Reflow soldering footprint part1 for HLQFN16 (SOT1688-1(SC))

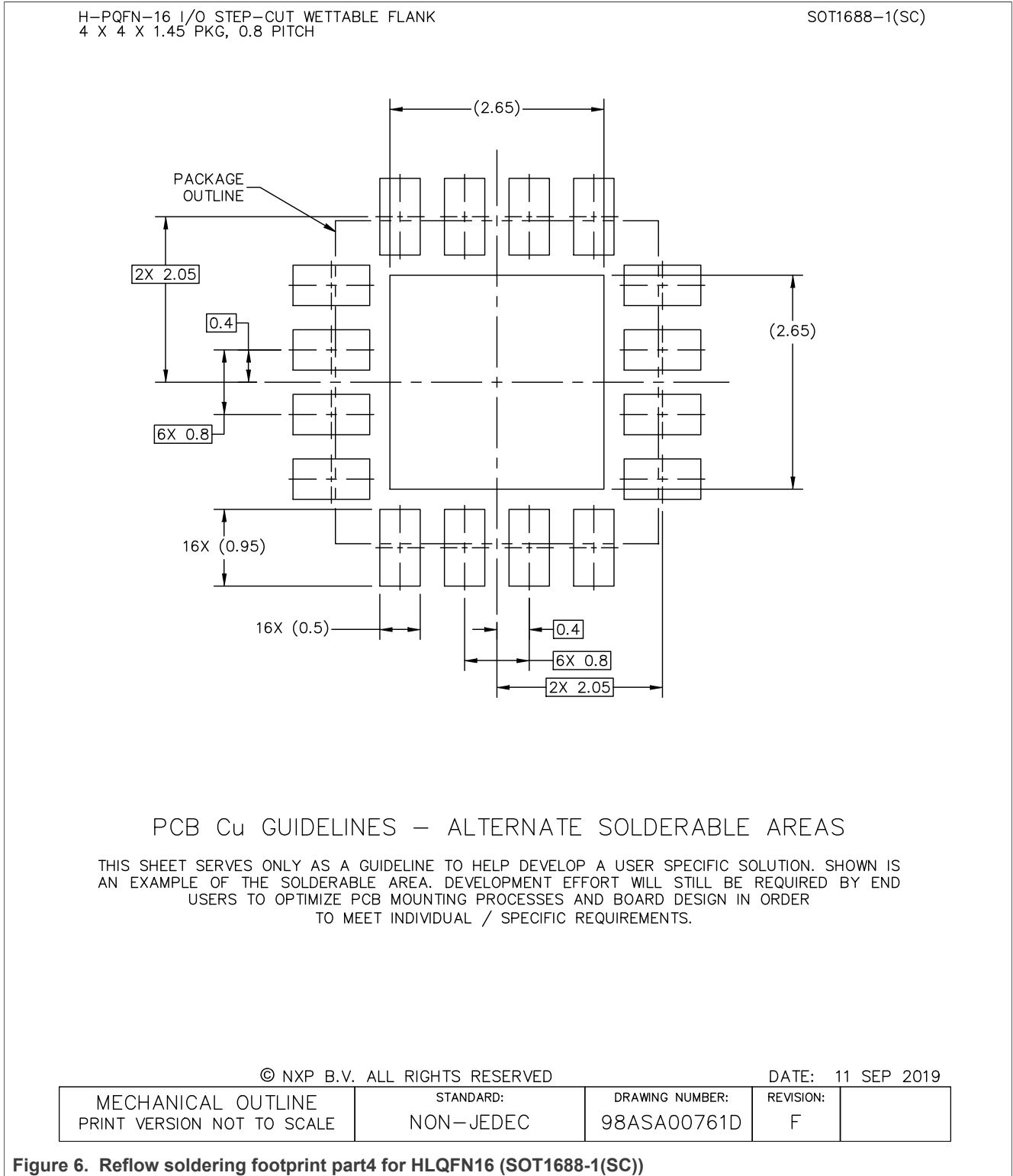
HLQFN16; plastic, thermal enhanced low profile quad flat non-leaded package; 16 terminals; 0.8 mm pitch; 4 mm x 4 mm x 1.45 mm body



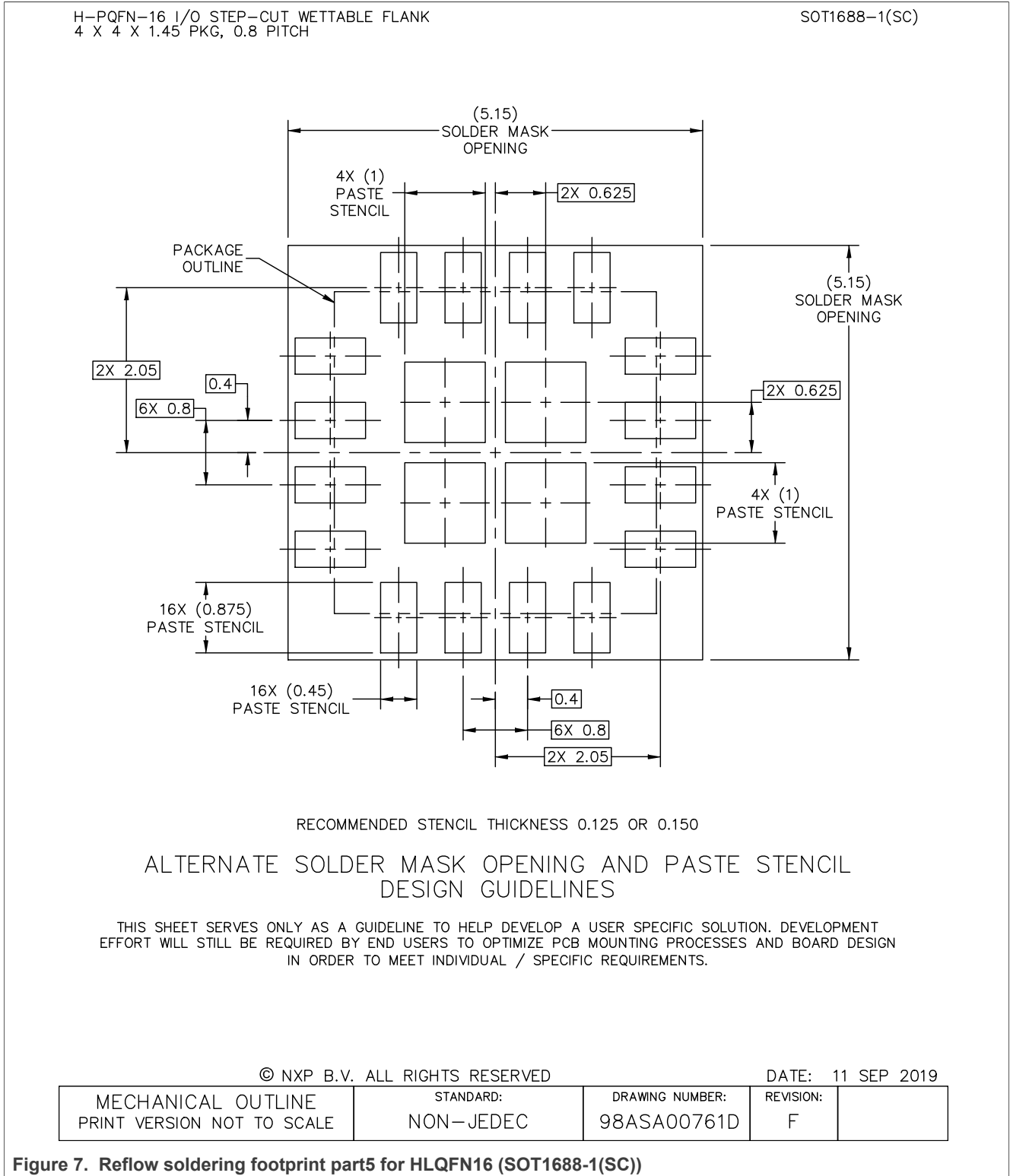
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H-PQFN-16 I/O STEP-CUT WETTABLE FLANK
4 X 4 X 1.45 PKG, 0.8 PITCH

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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. THIS IS A NON-JEDEC REGISTERED PACKAGE.
4.  COPLANARITY APPLIES TO LEADS AND DIE ATTACH FLAG.
5. MINIMUM METAL GAP SHOULD BE 0.15 MM.
6. RECOMMENDED STENCIL AND SOLDER PASTED AREA ARE IN SHEET 3 TO 5.

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DATE: 11 SEP 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA00761D	REVISION: F	
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Figure 8. Package outline note HLQFN16 (sot1688-1(SC))

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4 Legal information

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